

Title (en)  
CORRUGATED STRUCTURES AND METHOD FOR THERMOFORMING PACKAGES

Title (de)  
WELLPAPPE-BÖGEN UND VERFAHREN ZUM THERMOFORMEN VON VERPACKUNGEN

Title (fr)  
STRUCTURES ONDULEES ET PROCEDE POUR THERMOFORMER DES EMBALLAGES

Publication  
**EP 1646469 A1 20060419 (EN)**

Application  
**EP 04757147 A 20040721**

Priority  
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Abstract (en)  
[origin: WO2005009658A1] A corrugated structure (100) having a first flat layer (10), a first corrugated layer (20) secured to the first flat layer (10), a second flat layer (30) having a first side (31) and a second side (32), wherein the first side (31) is secured to the first corrugated layer (20) on a side opposite of the first flat layer, a coating layer (40) secured to the second side (32) of the second flat layer (30), wherein the coating layer (40) has a melting temperature of at least about 450 degrees Fahrenheit and chloroform-soluble extractives of at most about 0.5 milligrams per square inch.

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**B23B 29/06**

IPC 8 full level  
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Citation (search report)  
See references of WO 2005009658A1

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